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FOR IMMEDIATE RELEASE

Press Release

YINCAE: UF 158UL Redefines Underfill for Large Chips

03/11/2025 (Albany, NY) - YINCAE, a leading innovator in advanced materials solutions, today announced the launch of its groundbreaking underfill material, UF 158UL. This cutting-edge product is designed to meet the increasing demands of large format chips, offering unparalleled performance in room temperature flow, fast cure, and high reliability.

UF 158UL boasts exceptional flowability, allowing it to effortlessly fill gaps as small as 10 microns, even in large 100x100 mm chips. Its unique formulation ensures rapid curing at room temperature, significantly reducing production time and energy costs. Moreover, UF 158UL exhibits superior reliability, providing robust protection against thermal stress, moisture, and mechanical shock, ensuring long-term device performance.

"We are thrilled to introduce UF 158UL, a game-changer in underfill technology," said CTO of YINCAE, "With its exceptional flow, fast cure, and high reliability, UF 158UL empowers manufacturers to achieve unprecedented levels of efficiency and quality in the production of large format chips."

UF 158UL is ideal for a wide range of applications, including:

- High-performance computing
- Artificial intelligence
- Automotive electronics
- Aerospace systems

Key Features and Benefits:

- Room temperature flow for easy application
- Fast cure for increased throughput
- High reliability for long-term performance
- Excellent gap fill in 10-micron spaces
- Compatible with large 100x100 mm chips

YINCAE's UF 158UL is available immediately for purchase. For more information on YINCAE's UF 158UL underfill, or to learn more about the YINCAE product range, please email us at: info@yincae.com. You can also find more information by visiting our website: www.yincae.com

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Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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